

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

SAH  
#2A  
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Applicant(s): Mayer, Steven T.; Bhaskaran, Vijay; Patton, Evan E.; Jackson, Robert L.; Reid, Jonathan  
Assignee: Novellus Systems, Inc.  
Title: Process For Electroplating Metal Into Microscopic Recessed Features  
Serial No.: ~~Unknown~~ 09/716016  
Examiner: ~~Unassigned~~ Leudor  
Group Art Unit: ~~Unassigned~~ 1741  
Docket No.: M-7125-2D US

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San Jose, California  
November 16, 2000

BOX PATENT APPLICATION  
COMMISSIONER FOR PATENTS  
Washington, D. C. 20231

PRELIMINARY AMENDMENT

Dear Sir:

Please enter the following amendment before taking action on the merits of the above-referenced patent application.

IN THE SPECIFICATION

Page 1, line 11 After "This application", insert --is a divisional of U.S.

Application Serial No. 09/410,170 which--.

IN THE CLAIMS

Please cancel Claims 1-18, 20, and 26 - 28.

Please amend Claims 19, 21-23, and 25 as follows.

19. (Amended) A method of mitigating corrosion of a metal seed layer on the surface of recessed features caused by contact of said metal seed layer with an electroplating solution, said method comprising cathodically polarizing said metal seed layer with respect to said solution prior to or less than approximately 5 seconds following contact of said metal seed layer with said solution.

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